To,
The Investor,

Dear Investor,

Sub.: Private Placement Offer cum Application Letter by Bondada Engineering Limited

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We thank you for your willingness to subscribe to the Equity Shares of our Company.

Pursuant to your willingness and recording your name(s) and address in Form PAS-5, the Board of Directors and Shareholders of our Company has approved the issue of Equity Shares to you.

Please refer to this Private Placement Offer Letter attached herewith along with the Application Form.

You are requested to submit the Application Form and the payment details for the Equity Shares subscription.

Please note that the Private Placement Offer Letter and Application Form shall not carry any rights of renunciation.

Also note that the offer is valid up to Thursday, 23, January, 2025 ("Offer Closing Date"). The Company reserves the right to early close the Offer or extend the Offer and shall intimate such change to the Proposed Allottee.

In case of any query in relation to this Private Placement Offer cum Application Letter or this offer, you may contact Ms. Sonia Bidlan, Company Secretary and Compliance Officer, at the registered office of the Company or at E-mail: cs@bondada.net, or on +91 8099366546 for any further clarification.

We appreciate your response.

Thanking You,

For, Bondada Engineering Limited

Sonia Bidlan
Digitally signed by Sonia Bidlan
Date: 2025.01.20 13:27:22 +05'30'

Sonia Bidlan
CS & Compliance Officer

Date: 17 January, 2025
Place: Hyderabad